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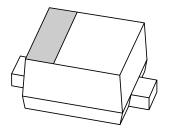
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



BAS716 Low-leakage diode

Product data sheet 2003 Nov 07



Low-leakage diode

BAS716

FEATURES

- Plastic SMD package
- Low leakage current: typ. 0.2 nA
- Switching time: typ. 0.6 μs
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

APPLICATION

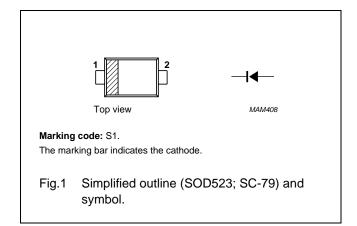
Low leakage current applications in surface mounted circuits.

DESCRIPTION

Epitaxial medium-speed switching diode with a low leakage current in an ultra small SOD523 (SC-79) SMD plastic package.

PINNING

PIN	DESCRIPTION	
1	cathode	
2	anode	



ORDERING INFORMATION

TYPE NUMBER		PACKAGE	
ITPE NUMBER	NAME	DESCRIPTION	VERSION
BAS716	_	plastic surface mounted package; 2 leads	SOD523

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		_	85	V
V _R	continuous reverse voltage		_	75	V
IF	continuous forward current	see Fig.2; note 1	_	200	mA
I _{FRM}	repetitive peak forward current		_	500	mA
I _{FSM}	non-repetitive peak forward current	square wave; $T_j = 25$ °C prior to surge; see Fig.4			
		t _p = 1 μs	_	4	Α
		t _p = 1 ms	_	1	Α
		t _p = 1 s	_	0.5	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

Note

1. Device mounted on a FR4 printed-circuit board.

Low-leakage diode

BAS716

ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 1 mA	0.77	0.9	V
		I _F = 10 mA	0.85	1	V
		I _F = 50 mA	0.92	1.1	V
		I _F = 150 mA	1.02	1.25	V
I _R	reverse current	V _R = 75 V	0.2	5	nA
		V _R = 75 V; T _j = 150 °C	3	80	nA
		V _R = 100 V	0.3	_	nA
C _d	diode capacitance	V _R = 0 V; f = 1 MHz; see Fig.6	2	_	pF
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA	0.6	3	μs

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	450	K/W
R _{th j-s}	thermal resistance from junction to soldering point	note 2	120	K/W

Notes

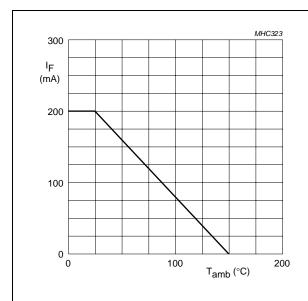
1. Device mounted on a FR4 printed-circuit board. Refer to SOD523 (SC-79) standard mounting conditions.

2. Soldering point of the cathode tab.

Low-leakage diode

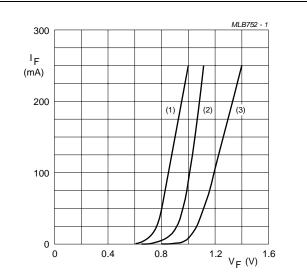
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GRAPHICAL DATA



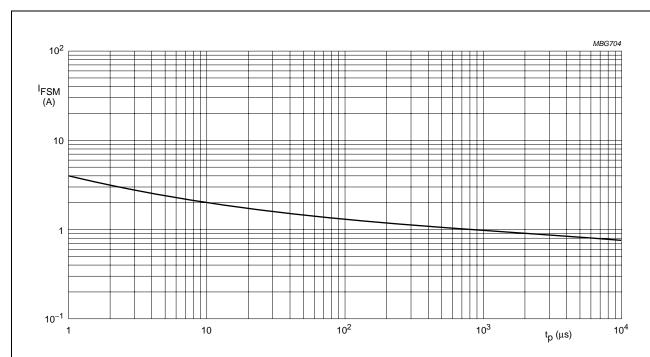
Device mounted on a FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_j = 150 \,^{\circ}\text{C}$; typical values.
- (2) $T_j = 25 \,^{\circ}\text{C}$; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



Based on square wave currents; $T_j = 25$ °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

Low-leakage diode

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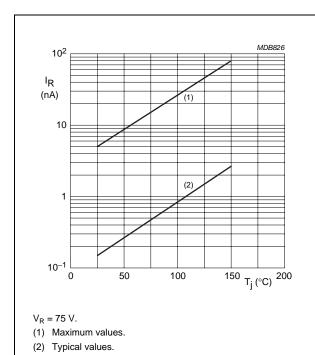
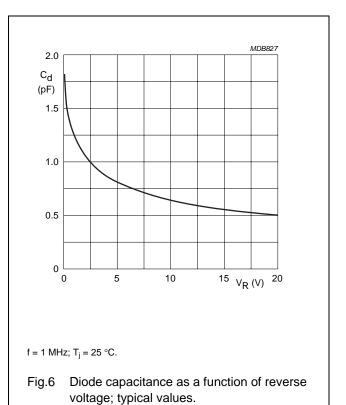
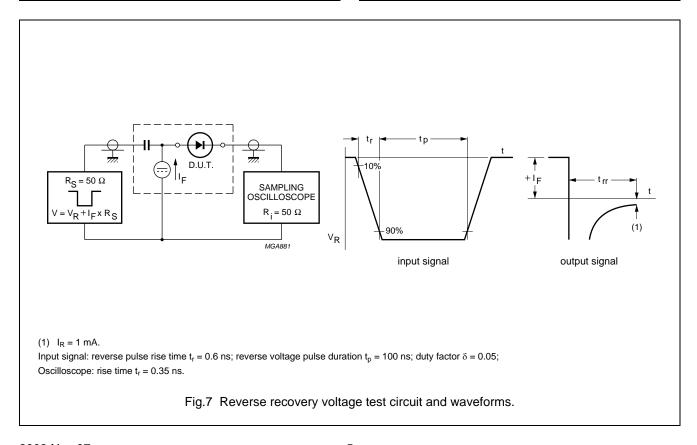


Fig.5 Reverse current as a function of junction temperature.





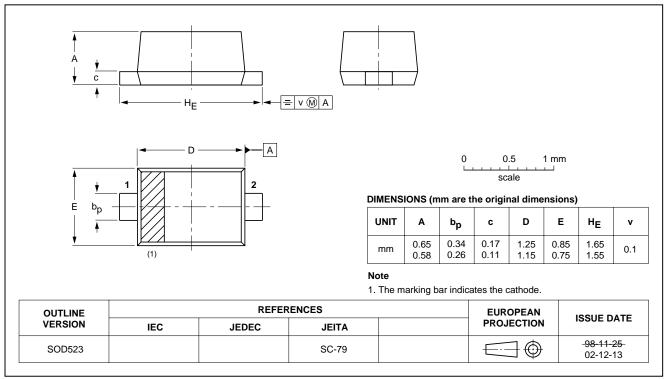
Low-leakage diode

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PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523



Low-leakage diode

BAS716

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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NXP Semiconductors

Customer notification

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Contact information

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